

Amendments to the Abstract are as follows:

~~According to the present invention, an electronic circuit unit is provided, by which, when an electronic circuit unit is mounted to a mother substrate, soldering reliability is enhanced and the shielding effect between the electronic circuit unit and the mother substrate is improved. An~~The electronic circuit unit ~~contains~~comprises a circuit board 4 having an upper face on which electronic components 2 are mounted and a lower face having a plurality of first land portions 3, and a connector member 4 disposed at a lower portion of the circuit board 4, wherein the connector member 4 has an insulating resin portion, 4a, a metallic shield plate 5 embedded in the insulating resin portion, 4a, and connector terminals 6 which are provided with first terminals 6a protruding from an upper face of the insulating resin portion 4a and second terminals 6e protruding from a lower face of the insulating resin portion, 4a, and the connector terminals 6 are configured such that the first terminals 6a over the upper face are electrically connected to the first land portions 3 and the second terminals 6e over the lower face are electrically connectable to second land portions 11 of a mother substrate, 10.